



IC Package
substrate



3D AFVI Handler

FCCSP 3D Inspection System (Strip type)

- Loading type: cassette to cassette system
- Bump application: flat, round, copper pillar, PoP (big ball & bump)
- Scan time: 8 sec per strip
- Laser beam thickness: 10um
- Inspection item: diameter, height, damaged, dimple, FM, bridge, missing, pitch, warp, coplanarity, void
- 3D sensor swath: 16mm

